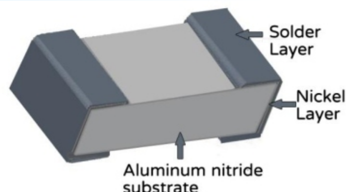
Features

-High thermal conductivity AlN substrate (170 W/mK)
-Electrically isolated
-Available with lead (Pb)-free wrap terminations
-AlN ceramic chips
-Low capacitance

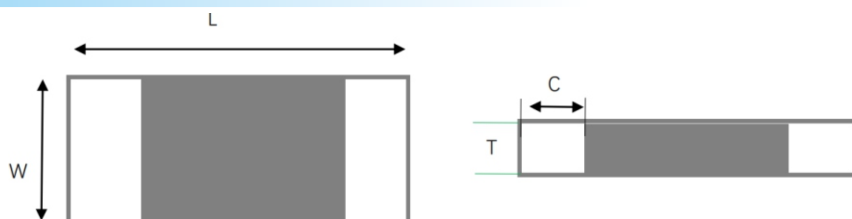
Application

-Switch mode power supply
-Converters
-RF amplifier

Construction



Dimensions



Type	Size (mm)	Item	L	W	C	T
NTJ	1225	Thermal Jumper	3.2±0.20	6.4±0.20	0.50±0.15	0.75±0.15
	2512		6.4±0.20	3.2±0.20	0.50±0.15	0.75±0.15

Ordering Information

Example

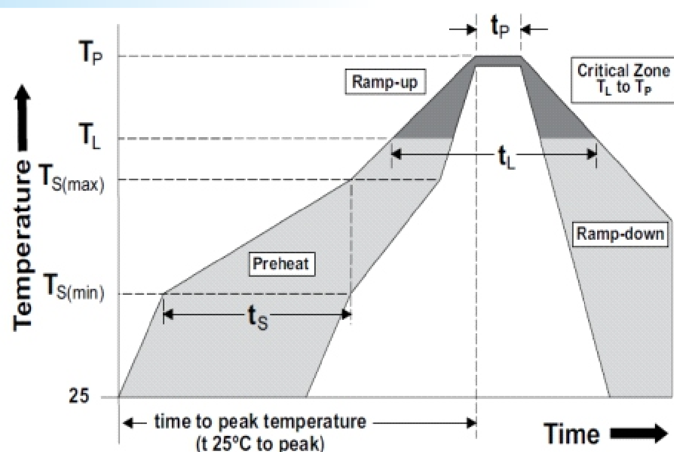
NTJ	2512	06	E
(1)	(2)	(3)	(4)
Type	Size (inch)	Thickness	Packaging

(1)Type:NTJ
(2)Size:1225、2512
(3)Thickness:06=0.6mm、075=0.75mm
(4)Packaging: E:Plastic ; 1: Q’ ty: 1KPcs/Reel、 2:Q’ ty: 2KPcs/Reel
3:Q’ ty: 3KPcs/Reel、 4:Q’ ty: 4KPcs/Reel

Typical Characteristics

Item / Type	Thermal resistance (℃/W), TR	Thermal conductance (mW/℃), TC	Capacitance (pF)@1KHz	Dielectric withstanding voltage kVAC, RMS (60 Hz)	Operating temperature range	Storage temperature range
NTJ (1225)	4	250	1.1	>1.5	-65~+150℃	-65~+150℃
NTJ (2512)	15	67	1.0			

IR Reflow-Soldering Profile



Reflow Condition		Pb – Free assembly
Pre heat	- Temperature Min (Ts(min))	150℃
	- Temperature Max (Ts(max))	200℃
	- Time (Min to Max) (ts)	60 – 120 secs
Average ramp up rate (Liquidus Temp (TL) to peak		5℃ /second max
Ts(max) to TL - Ramp-up Rate		5℃ /second max
	- Temperature (TL) (Liquidus)	217℃
	- Time (tL)	60 – 150 seconds
Peak Temperature (TP)		260℃
Time within 5℃ of actual peak Temperature (tp)		10 – 30 seconds
Ramp-down Rate		6℃ /second max
Time 25℃ to peak Temperature (TP)		8 minutes Max.
Wave Soldering		260℃, 10 seconds max.
Hand Soldering		350℃, 5 seconds max.

Performance

Item	Requirement	Test Method
Solderability	J-STD-002,method B and B1	Over 95%of termination must be covered with solder.
Resistance to Solder Heat	T=260+/-5℃ solder,10+/-1 sec dwell	Without solder leaching
Board Flex	AEC-Q200 Method 005	Without damaged &Crack